



Click [here](#) for the 3D model.

### Dimensions

|           |                 |
|-----------|-----------------|
| Chip Size | 0402            |
| L         | 1mm +/-0.05mm   |
| W         | 0.5mm +/-0.05mm |
| T         | 0.5mm +/-0.05mm |
| S         | 0.3mm MIN       |
| B         | 0.3mm +/-0.1mm  |

### Packaging Specifications

|                    |          |
|--------------------|----------|
| Packaging          | Cut Reel |
| Packaging Quantity | 500      |

### General Information

|                  |   |
|------------------|---|
| Series           | SMD Indust COG HT200C                               |
| Style            | SMD Chip  |
| Description      | SMD, MLCC, High Temperature, Ultra-Stable, Low Loss |
| Features         | High Temp, Ultra-Stable, Low Loss                   |
| RoHS             | Yes   |
| Termination      | Tin   |
| Marking          | No  |
| AEC-Q200         | No  |
| Component Weight | 1.06 mg   |
| Shelf Life       | 78 Weeks  |
| MSL              | 1   |

### Specifications

|  |                           |
|--|---------------------------|
| Capacitance  | 1000 pF                   |
| Measurement Condition  | 1 MHz 1.0Vrms             |
| Capacitance Tolerance  | 5%                        |
| Voltage DC   | 50 VDC                    |
| Dielectric Withstanding Voltage                                    | 125 VDC                   |
| Temperature Range  | -55/+200°C                |
| Temperature Coefficient  | COG                       |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1MegaHz 1.0Vrms |
| Dissipation Factor   | 0.1% 1 MHz 1.0Vrms        |
| Aging Rate   | 0% Loss/Decade Hour       |
| Insulation Resistance  | 100 GOhms                 |